

**FEE TRANSMITTAL**

Electronic Version v08

Stylesheet Version v08.0

**Title of  
Invention****METHOD FOR FORMING ROBUST SOLDER INTERCONNECT STRUCTURES  
BY REDUCING EFFECTS OF SEED LAYER UNDERETCHING**

Application Number :

Date :

First Named Applicant: Kamalesh K. Srivastava

Attorney Docket Number: FIS920030359US1

**TOTAL FEE AUTHORIZED \$ 810**

Patent fees are subject to annual revisions on or about October 1st of each year.

Filing as large entity

**BASIC FILING FEE**

Fee Description	Fee Code	Amount \$	Fee Paid \$
Utility Filing Fee	1001	770	770
Subtotal For Basic Filing Fees: \$ 770			

**EXTRA CLAIM FEES**

Fee Description	Extra Claim	Fee Code	Amount \$	Fee Paid \$
Total Claims : 20	0	1202	18	0
Independent Claims : 3	0	1201	86	0
Subtotal For Extra Claims Fees: \$ 0				

**ASSIGNMENT FEES**

Fee Description	Property Number	Quantity	Fee Code	Amount \$	Fee Paid \$
Recording Each Patent Assignment Per Property Fee	00000000	1	8021	40	40
Subtotal For Additional Fees: \$40					

**AUTHORIZED BILLING INFORMATION****The commissioner is hereby authorized to charge indicated fees and credit any  
overpayments to:**

Deposit account number: 090458

Deposit name: INTERNATIONAL BUSINESS MACHINES  
CORPORATION

Deposit authorized name: JAMES J. CIOFFI

Signature: JAMES J. CIOFFI/ S /

Date (YYYYMMDD):

2004-03-16

Charge Assignment Fees Required Under 37 C.F.R. Section 1.21 (h).

Charge Any Additional Fee Required Under 37 C.F.R. Sections 1.16 and 1.17.